



Product Change Notification: MAAN-22EXSN768

Date:

28-Oct-2026

Product Category:

Motor Control Sips

Notification Subject:

CCB 8530 Initial Notice: Qualification of 8600NP as a new die attach material and CV8715BUA-9 as a new mold compound material for selected dsPIC33CDV256MP506, dsPIC33CDV128MP506, dsPIC33CDVC256MP506, dsPIC33CDVC128MP506, dsPIC33CDV128MP206 and dsPIC33CDV256MP206 device families available in 64L VGQFN (9x9x0.927) package at NSEB assembly site.

Affected CPNs:

[MAAN-22EXSN768_Affected_CPN_10282026.pdf](#)

[MAAN-22EXSN768_Affected_CPN_10282026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of 8600NP as a new die attach material and CV8715BUA-9 as a new mold compound material for selected dsPIC33CDV256MP506, dsPIC33CDV128MP506, dsPIC33CDVC256MP506, dsPIC33CDVC128MP506, dsPIC33CDV128MP206 and dsPIC33CDV256MP206 device families available in 64L VGQFN (9x9x0.927) package at NSEB assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change
Assembly Site	UTAC Thai Limited (UTL-1) LTD. (NSEB)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	No
Wire Material	CuPdAu	CuPdAu	No

		Pre Change		Post Change		Change
Die Attach Material		8600 (PFAS)		8600NP (PFAS-free)		Yes
Molding Compound Material		G700LTD	CV8715BT-7	G700LTD	CV8715BUA-9	Yes
Lead-Frame Material		EFTEC-64T		EFTEC-64T		No
Lead-Frame Paddle Size	DAP#1	2.29x3.63mm (90.16 x 142.91 mil)		2.29x3.63mm (90.16 x 142.91 mil)		No
	DAP#2	3.60x3.30mm (141.73 x 129.92 mil)		3.60x3.30mm (141.73 x 129.92 mil)		No
	DAP#3	2.03x1.50mm (79.92 x 59.06 mil)		2.03x1.50mm (79.92 x 59.06 mil)		No
Lead-Frame DAP Surface Prep		Selective PPF (NiPdAu)		Selective PPF (NiPdAu)		No
Lead-Frame Design		No Change.				

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying 8600NP as a new die attach material and CV8715BUA-9 as a new mold compound material at NSEB assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: March 2027

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	October 2026					>	March 2027			
Work Week	40	41	42	43	44		09	10	11	12
Initial PCN Issue Date					x					
Qual Report Availability							x			
Final PCN Issue Date							x			

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: October 28, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_MAAN-22EXSN768 Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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